



POLYIMIDE DISCS **P/N 12-10-D-A-**

Die cut polyimide film with pressure sensitive silicone adhesive on a clear split back liner is designed to protect areas on circuit boards during wave soldering and provides optimal performance in electrical and thermal insulation.



Ideal for wave soldering, insulating circuit boards

- Has high dielectric strength
- Highly resistant to heat and chemicals.
- Puncture and tear resistant at high temperatures.
- Silicone adhesive protection without leaving any residue
- Temperature up to 500°F / 260°C

Available sizes: ¼ , ½ , 3/8 , 5/16 and ¾, Inch diameters

Specification	Values
General	
Color Amber	Amber
Material	Polyimide Film
Adhesive	Silicon
Film thickness	1 mil or 0.025 mm
Total thickness	2.5 mil or 0.062 mm
Length	36 Yards
Physical Properties	
Adhesion to steel	1.3-1.5 lbs./inch or 0.6-.07 kg/25mm
Tensile strength	22-29 lbs./inch or 10-13 kg/25mm
Elongation at break (%)	≥ 40 %
Temperature Resistance	
Temperature	500°F / 260°C
Resistance to: acids, oils, solvents Excellent	

Static Charge @ 50% R.H 70°F in ESD Controlled Environment

Important: While the information contained herein results from extensive testing on these materials and/or information supplied by other manufacturers, accuracy and reliability of such tests and information cannot be guaranteed, thus requiring limits on warranty. User assumes all liability regarding damage or loss arising from use of product. User shall determine the appropriateness of these materials for intended application and assumes total liability in the event of aforementioned damages.